

07-16-1999



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101092676

To the Honorable Commissioner of Patents and Trademarks, please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Hua-Shu Wu, Chun-Hung Peng  
Hung-Chan Lin

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other

Execution Date: June 2 and 7, 1999

2. Name and address of receiving party(ies):

Name: Utek Semiconductor Corp.

Internal Address:

Street Address: No. 5, Creation Road 2  
Science-Based Industrial Park

City: Hsinchu, Taiwan State: ZIP:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

10588 U.S. PTO  
09/347977  
07/05/99

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: June 2, 7, 1999

A. Patent Application No.(s)

091347977

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Raymond Sun

Internal Address:

Street Address: 12420 Woodhall Way

City: Tustin State: CA ZIP: 92782

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 90.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

07/15/1999 RTHA11 00000297 09347977

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Raymond Sun

Name of Person Signing

Signature

7-6-99

Date

# ASSIGNMENT

Attorney Docket No. Yuso-062

- (1-8) Insert Name(s) of Inventor(s)
- (1) Hua-Shu Wu (5) \_\_\_\_\_
- (2) Chun-Hung Peng (6) \_\_\_\_\_
- (3) Hung-Chan Lin (7) \_\_\_\_\_
- (4) \_\_\_\_\_ (8) \_\_\_\_\_
- In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to
- (1-9) Insert name of Assignee (9) UTEK SEMICONDUCTOR CORPORATION
- (10) Insert state of Incorporation of Assignee (10) Hsinchu, Taiwan
- (11) Insert address of Assignee (11) of No.5, Creation Rd.2, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.  
(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as
- (12) Insert identification of Invention, such as Title, Case Number or Foreign Application Number (12) METHOD OF FORMING SELF-ALIGNED UNLANDED VIA HOLES  
(Case No. 870743.IE1)  
for which the undersigned has (have) executed an application for patent in the United States of America
- (13) Insert Date of Signing of Application (13) on June 2, June 7, 1999

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as the Assignee may does necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the international Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) The undersigned hereby grants RAYMOND SUN, Reg. No.35,699, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent & Trademark Office for recordation of this document.

Date: <u>June 7, 99</u>	Name of Inventor: <u>Hua-Shu Wu</u>	(SEAL)
Date: <u>June 2, 1999</u>	Name of Inventor: <u>Chun-Hung Peng</u>	(SEAL)
Date: <u>June 2, 1999</u>	Name of Inventor: <u>Hung Chan Lin</u>	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)
Date: _____	Name of Inventor: _____	(SEAL)